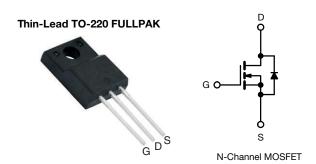
Vishay Siliconix

E Series Power MOSFET



PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	550)
R _{DS(on)} max. (Ω) at 25 °C	V _{GS} = 10 V	0.380
Q _g max. (nC)	50	
Q _{gs} (nC)	6	
Q _{gd} (nC)	10	
Configuration	Sing	le

FEATURES

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



APPLICATIONS

- Computing
 - PC silver box / ATX power supplies
- Lighting
 - Two stage LED lighting
- Consumer electronics
- · Applications using hard switched topologies
 - Power factor correction (PFC)
 - Two switch forward converter
 - Flyback converter
- Switch mode power supplies (SMPS)

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA12N50E-E3
Lead (Pb)-free and halogen-free	SiHA12N50E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	500		
Gate-source voltage		V_{GS}	± 30	V		
Continuous drain augment /T 150 °C\ 6	T ₀	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		10.5		
Continuous drain current (T _J = 150 °C) ^e	V _{GS} at 10 V	T _C = 100 °C	I _D	6.6	A	
Pulsed drain current ^a			I _{DM}	21		
Linear derating factor				0.91	W/°C	
Single pulse avalanche energy b			E _{AS}	103	mJ	
Maximum power dissipation			P_{D}	32	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	V _{DS} = 0 V to 80 % V _{DS}		d\//d+	70	V/ns	
Reverse diode dV/dt ^d			dV/dt	27	V/IIS	
Soldering recommendations (peak temperature) c	for	10 s		300	°C	
Mounting torque	M3 s	screw		0.6	Nm	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_a = 25 Ω , I_{AS} = 2.7 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C
- e. Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	3.9	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					l .		
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		500	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.60	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	=.	± 1	μΑ
Zero gate voltage drain current		V _{DS} =	V _{DS} = 500 V, V _{GS} = 0 V		=.	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 400 \	V, V _{GS} = 0 V, T _J = 125 °C	-	=.	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 6 A	-	0.330	0.380	Ω
Forward transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 6 A		-	3.1	-	S
Dynamic				•			•
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	886	-	pF
Output capacitance	C _{oss}			-	52	-	
Reverse transfer capacitance	C _{rss}			-	6	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	45	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	131	-	
Total gate charge	Qg			-	25	50	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 6 A, V_{DS} = 400 V$	-	6	-	nC
Gate-drain charge	Q _{gd}			-	10	-	
Turn-on delay time	t _{d(on)}			-	13	26	
Rise time	t _r	$V_{DD} = 400 \text{ V}, I_D = 6 \text{ A},$		-	16	32	ns
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{DD} = 400 \text{ V}, I_D = 6 \text{ A},$ $V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		29	58	
Fall time	t _f			-	12	24	
Gate input resistance	R_g	f = 1 MHz, open drain		-	0.92	-	Ω
Drain-Source Body Diode Characteristic	s						•
Continuous source-drain diode current	Is	MOSFET sym	MOSFET symbol showing the		-	10.5	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	21	_ A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 7.5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 6 \text{ A},$ $dI/dt = 100 \text{ A/µs}, V_R = 25 \text{ V}$		-	244	-	ns
Reverse recovery charge	Q _{rr}			-	2.5	-	μC
Reverse recovery current	I _{RRM}			_	19	_	Α

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

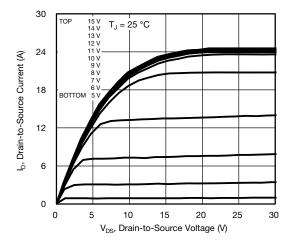


Fig. 1 - Typical Output Characteristics

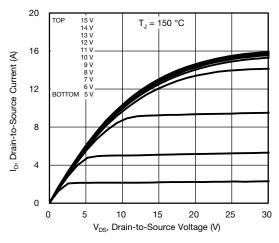


Fig. 2 - Typical Output Characteristics

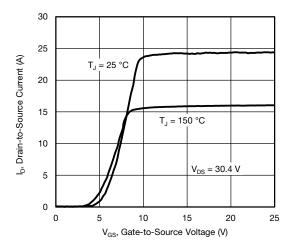


Fig. 3 - Typical Transfer Characteristics

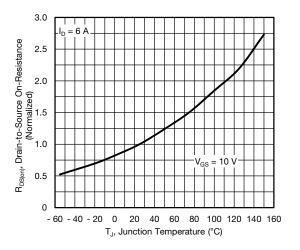


Fig. 4 - Normalized On-Resistance vs. Temperature

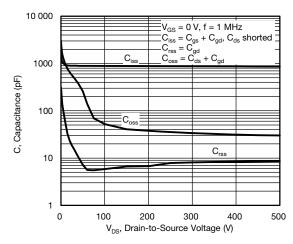


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

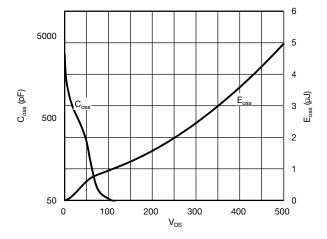


Fig. 6 - Coss and Eoss vs. VDS



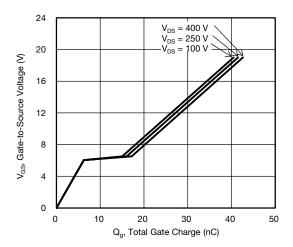


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

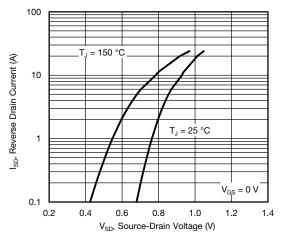


Fig. 8 - Typical Source-Drain Diode Forward Voltage

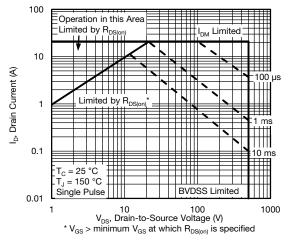


Fig. 9 - Maximum Safe Operating Area

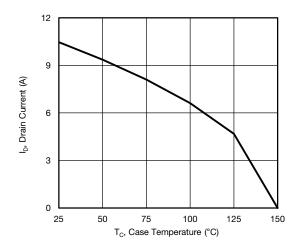


Fig. 10 - Maximum Drain Current vs. Case Temperature

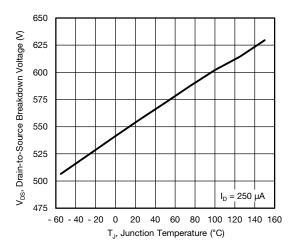


Fig. 11 - Temperature vs. Drain-to-Source Voltage



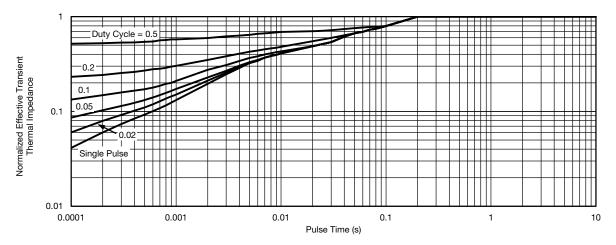


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

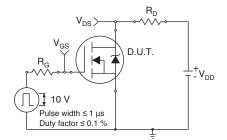


Fig. 13 - Switching Time Test Circuit

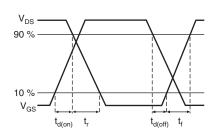


Fig. 14 - Switching Time Waveforms

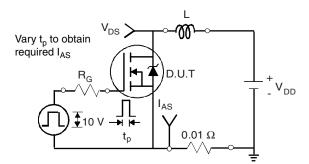


Fig. 15 - Unclamped Inductive Test Circuit

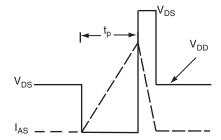


Fig. 16 - Unclamped Inductive Waveforms

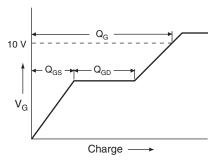


Fig. 17 - Basic Gate Charge Waveform

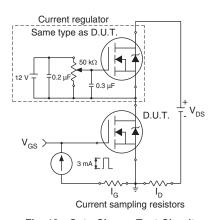
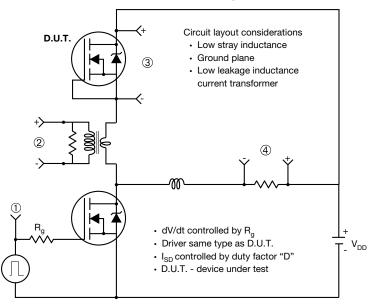


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



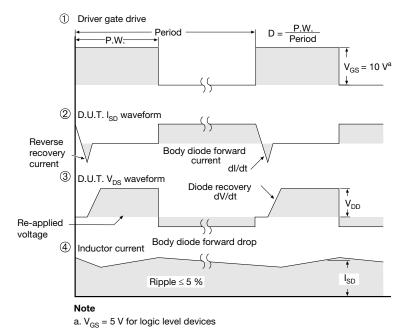
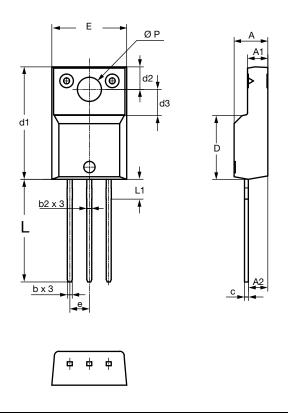


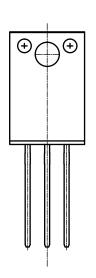
Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead





SYMBOL		DIMEN	ISIONS	
	MILLIN	IETERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
А	4.30	4.70	0.169	0.185
A1	2.50	2.90	0.098	0.114
A2	2.40	2.80	0.094	0.110
b	0.60	0.80	0.024	0.031
b2	0.60	0.90	0.024	0.035
С	-	0.60	-	0.024
D	8.30	8.70	0.327	0.342
d1	14.70	15.30	0.579	0.602
d2	2.90	3.10	0.114	0.122
d3	3.30	3.70	0.130	0.146
Е	9.70	10.30	0.382	0.406
е	2.50	2.70	0.098	0.106
L	13.40	13.80	0.528	0.543
L1	1.00	2.80	0.039	0.110
ØP	3.00	3.40	0.118	0.134

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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Vishay

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